

Thermal RC network (Foster)

SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
th(j-mb)	thermal resistance from junction to mounting base		-	-	0.43	K/W
	Cth ₁	2.727E-04 F		今 .	t:	
	Cth ₂	1.961E-03 F		↓	tj	
	Cth ₃	1.472E-03 F			└─ ┿──┘	
	Cth ₄	5.515E-03 F				
	Cth ₅	1.889E-02 F		L	ן יי ד ז ייי	
	Cth ₆	3.370E-02 F				
	Cth ₇	7.373E-01 F		Г	$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$	
	Cth ₈	2.812E+02 F			$\int Rth_2 + Cth_2$	2
	Rth₁	3.269Ε-04 Ω				
	Rth ₂	6.428E-04 Ω		Г	$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$	
	Rth ₃	7.505E-03 Ω			Rth3 🛨 Cth3	5
	Rth₄	1.817E-02 Ω			ᡗ᠋	
	Rth₅	6.176E-02 Ω			_	
	Rth ₆	2.678E-01 Ω			Rth4 📥 Cth4	
	Rth ₇	7.287E-02 Ω				ŀ
	Rth ₈	6.467E-04 Ω	((P)		
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					Rth7 = Cth7	,
Part:	BUK765R0-100E					8
ate:	11/4/2013					
Nodel Rth	0.43 K/W					
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